

MOSFET - Power, Single N-Channel, TOLL



ON Semiconductor®

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NTBLS1D5N08MC 80 V, 1.53 mΩ, 298 A

Features

- Low $R_{DS(on)}$ to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- Lowers Switching Noise/EMI
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- Power Tools, Battery Operated Vacuums
- UAV/Drones, Material Handling
- BMS/Storage, Home Automation

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Value	Unit	
Drain-to-Source Voltage		V_{DSS}	80	V	
Gate-to-Source Voltage		V_{GS}	± 20	V	
Continuous Drain Current $R_{\theta JC}$ (Note 2)	Steady State	$T_C = 25^\circ\text{C}$	I_D	298	A
		$T_C = 25^\circ\text{C}$	P_D	250	W
Continuous Drain Current $R_{\theta JA}$ (Notes 1, 2)	Steady State	$T_A = 25^\circ\text{C}$	I_D	32	A
		$T_A = 25^\circ\text{C}$	P_D	2.9	W
Pulsed Drain Current	$T_A = 25^\circ\text{C}, t_p = 10 \mu\text{s}$	I_{DM}	4487	A	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to +150	$^\circ\text{C}$	
Source Current (Body Diode)		I_S	192	A	
Single Pulse Drain-to-Source Avalanche Energy ($I_{L(pk)} = 31 \text{ A}, L = 3 \text{ mH}$)		E_{AS}	1441	mJ	
Lead Temperature Soldering Reflow for Soldering Purposes (1/8" from case for 10 s)		T_L	260	$^\circ\text{C}$	

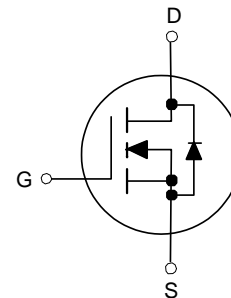
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case – Steady State (Note 2)	$R_{\theta JC}$	0.5	$^\circ\text{C/W}$
Junction-to-Ambient – Steady State (Note 2)	$R_{\theta JA}$	43	

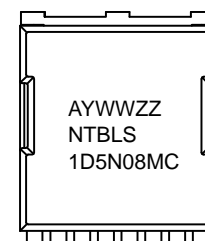
1. Surface-mounted on FR4 board using a 1 in² pad size, 1 oz. Cu pad.
2. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

$V_{(BR)DSS}$	$R_{DS(ON)} \text{ MAX}$	$I_D \text{ MAX}$
80 V	1.53 mΩ @ 10 V	298 A
	3.7 mΩ @ 6 V	



MO-299A
TOLL
CASE 100CU

MARKING DIAGRAM



NTBLS1D5N08MC = Specific Device Code
 A = Assembly Location
 Y = Year
 WW = Work Week
 ZZ = Lot Traceability

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

NTBLS1D5N08MC

Table 1. ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units	
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$I_D = 250 \mu\text{A}, V_{GS} = 0 \text{ V}$	80	-	-	V	
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$	$I_D = 250 \mu\text{A}, \text{ref to } 25^\circ\text{C}$	-	78	-	mV/ $^\circ\text{C}$	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}$	$T_J = 25^\circ\text{C}$	-	-	1	μA
			$T_J = 125^\circ\text{C}$	-	-	100	μA
Gate-to-Source Leakage Current	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA	
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS} = V_{DS}, I_D = 710 \mu\text{A}$	2.0	3.0	4.0	V	
Negative Threshold Temperature Coefficient	$V_{GS(th)}/T_J$	$I_D = 710 \mu\text{A}, \text{ref to } 25^\circ\text{C}$	-	-8.3	-	mV/ $^\circ\text{C}$	
Drain-to-Source On Resistance	$R_{DS(on)}$	$V_{GS} = 10 \text{ V}, I_D = 80 \text{ A}$	-	1.30	1.53	m Ω	
Drain-to-Source On Resistance	$R_{DS(on)}$	$V_{GS} = 6 \text{ V}, I_D = 63 \text{ A}$	-	2.0	3.7	m Ω	
Forward Transconductance	g_{FS}	$V_{DS} = 5 \text{ V}, I_D = 80 \text{ A}$	-	220	-	S	
Gate-Resistance	R_G	$T_A = 25^\circ\text{C}$	-	0.7	-	Ω	
CHARGES & CAPACTIANCES							
Input Capacitance	C_{iss}	$V_{GS} = 0 \text{ V}, V_{DS} = 40 \text{ V}, f = 1 \text{ MHz}$	-	8170	-	pF	
Output Capacitance	C_{oss}		-	3025	-	pF	
Reverse Transfer Capacitance	C_{rss}		-	82	-	pF	
Total Gate Charge	$Q_{G(tot)}$	$V_{GS} = 10 \text{ V}, V_{DS} = 40 \text{ V}, I_D = 80 \text{ A}$	-	111	-	nC	
Threshold Gate Charge	$Q_{G(th)}$		-	22	-		
Gate-to-Source Charge	Q_{gs}		-	35	-		
Gate-to-Drain Charge	Q_{gd}		-	23	-		
Output Charge	Q_{oss}		-	166	-		
Sync Charge	Q_{sync}		-	94	-		
Plateau Voltage	V_P		-	5	-	V	
SWITCHING CHARACTERISTICS, $V_{GS} = 10 \text{ V}$ (Note 3)							
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = 10 \text{ V}, V_{DS} = 40 \text{ V}, I_D = 80 \text{ A}, R_G = 6 \Omega$	-	38	-	ns	
Rise Time	t_r		-	34	-	ns	
Turn-Off Delay Time	$t_{d(off)}$		-	74	-	ns	
Fall Time	t_f		-	37	-	ns	
DRAIN-SOURCE DIODE CHARACTERISTICS							
Forward Diode Voltage	V_{SD}	$I_S = 80 \text{ A}, V_{GS} = 0 \text{ V}$	$T_J = 25^\circ\text{C}$	-	0.8	1.3	V
		$I_S = 80 \text{ A}, V_{GS} = 0 \text{ V}$	$T_J = 125^\circ\text{C}$	-	0.7	-	V
Reverse Recovery Time	t_{rr}	$I_F = 40 \text{ A}, di/dt = 300 \text{ A}/\mu\text{s}$	-	19	-	nS	
Reverse Recovery Charge	Q_{rr}		-	42	-	nC	
Reverse Recovery Time	t_{rr}	$I_F = 40 \text{ A}, di/dt = 1000 \text{ A}/\mu\text{s}$	-	17	-	nS	
Reverse Recovery Charge	Q_{rr}		-	121	-	nC	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Switching characteristics are independent of operating junction temperatures

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TYPICAL CHARACTERISTICS

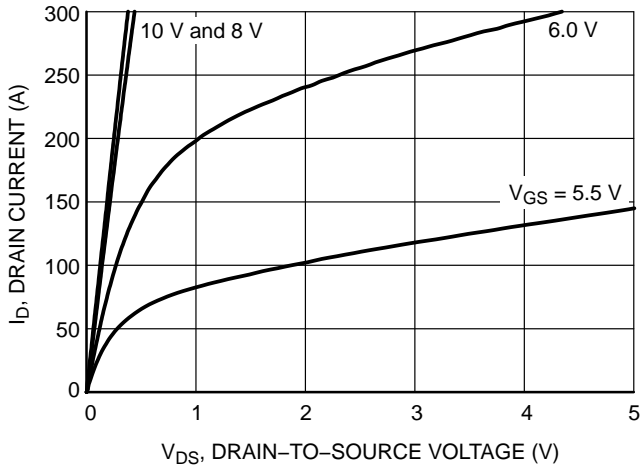


Figure 1. On-Region Characteristics

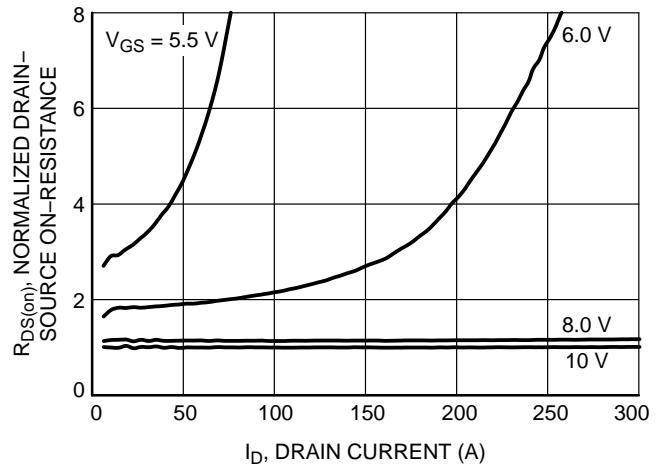


Figure 2. $R_{DS(on)}$ Normalized vs. I_D

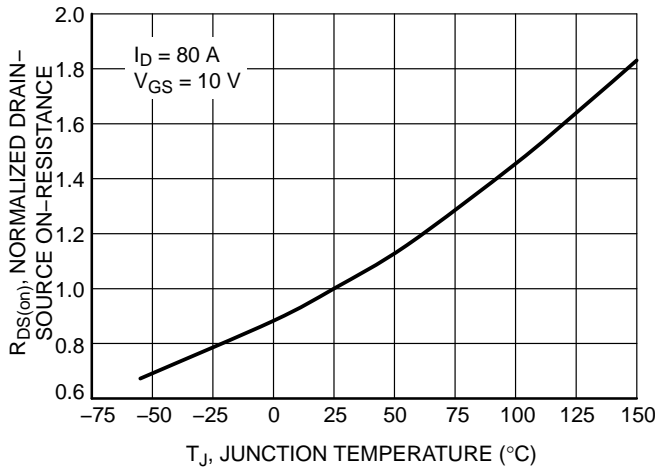


Figure 3. $R_{DS(on)}$ vs. Junction Temperature

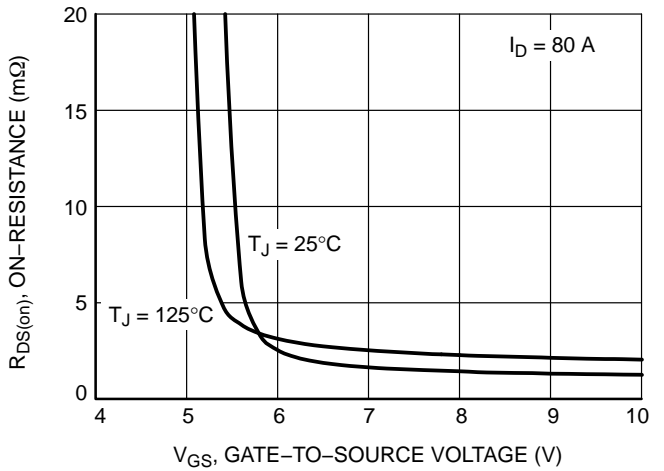


Figure 4. On-Resistance vs. Gate-to-Source Voltage

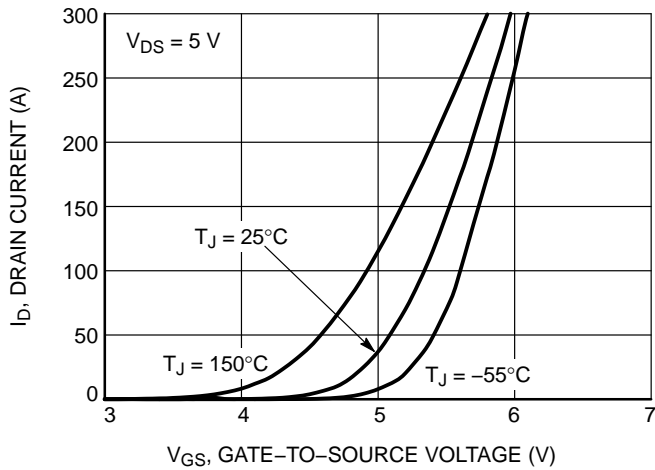


Figure 5. Drain Current vs. Gate-to-Source Voltage

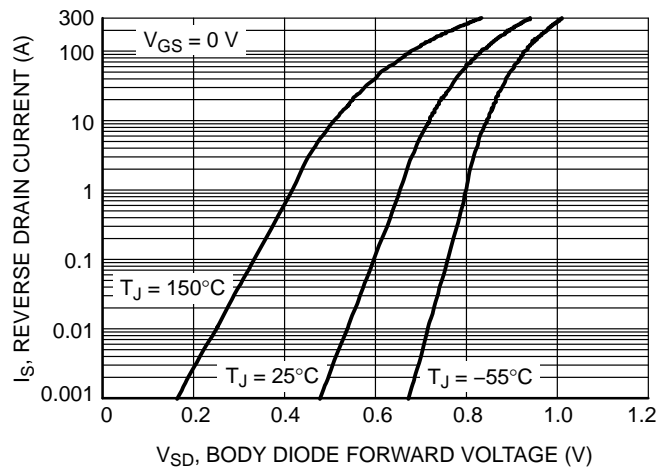


Figure 6. Reverse Drain Current vs. Body Diode Forward Voltage

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TYPICAL CHARACTERISTICS

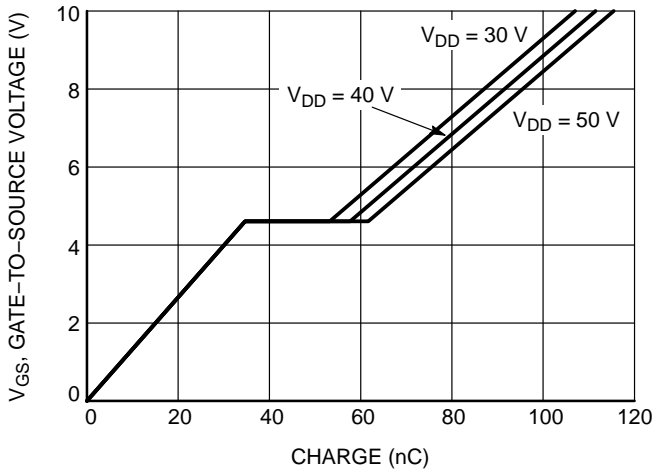


Figure 7. Gate Charge

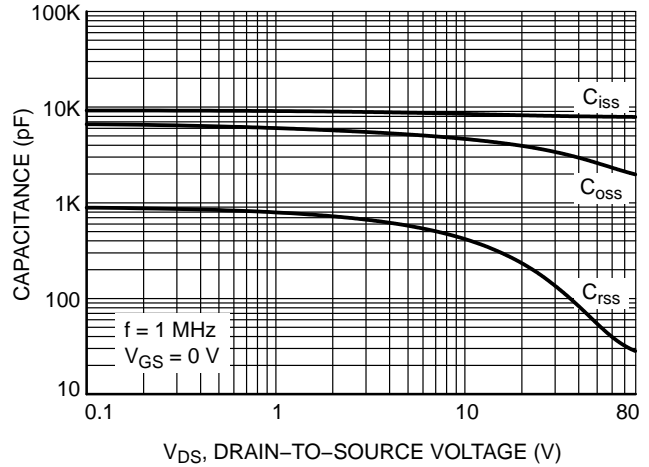


Figure 8. Capacitance Variation

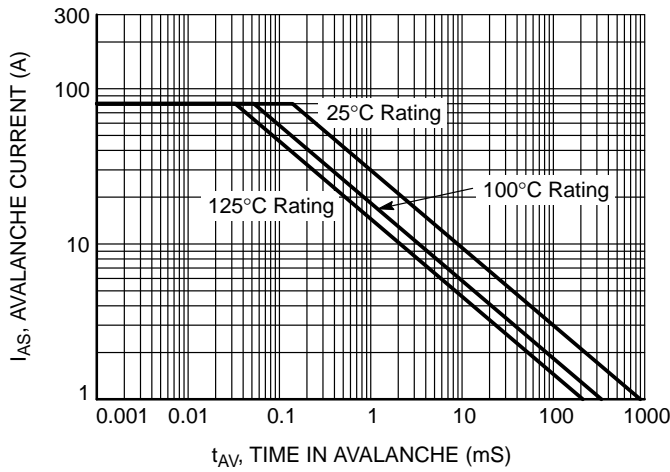


Figure 9. UIL

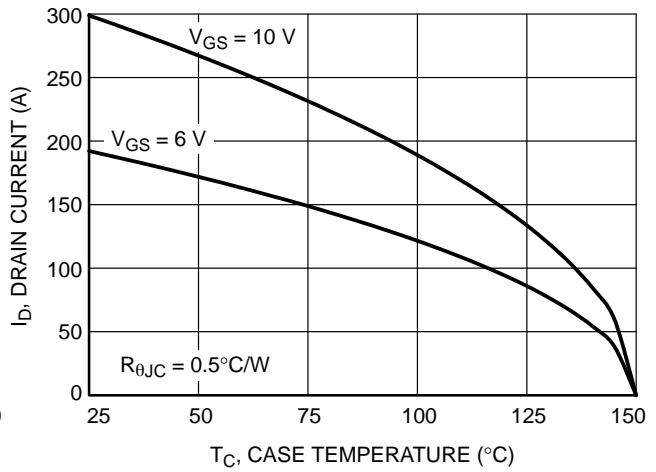


Figure 10. Drain Current vs. Case Temperature

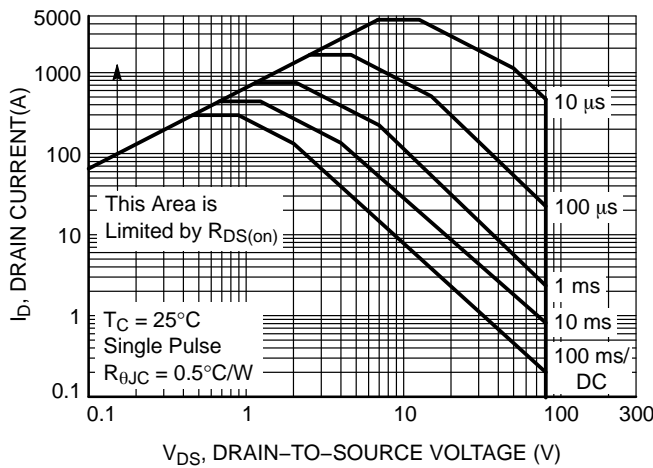


Figure 11. Maximum Rated Forward Biased Safe Operating Area

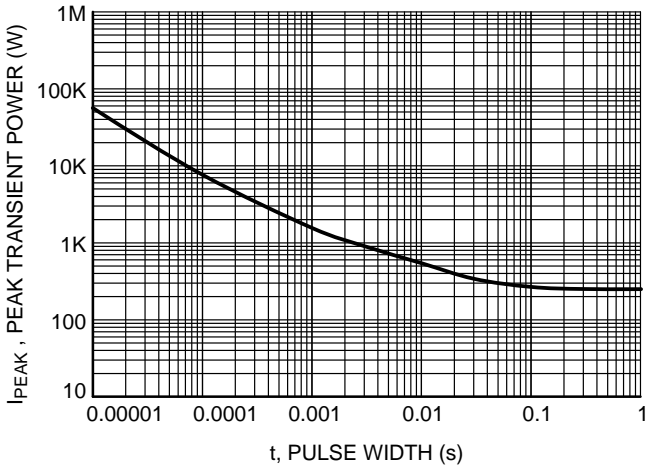


Figure 12. Peak Power

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TYPICAL CHARACTERISTICS

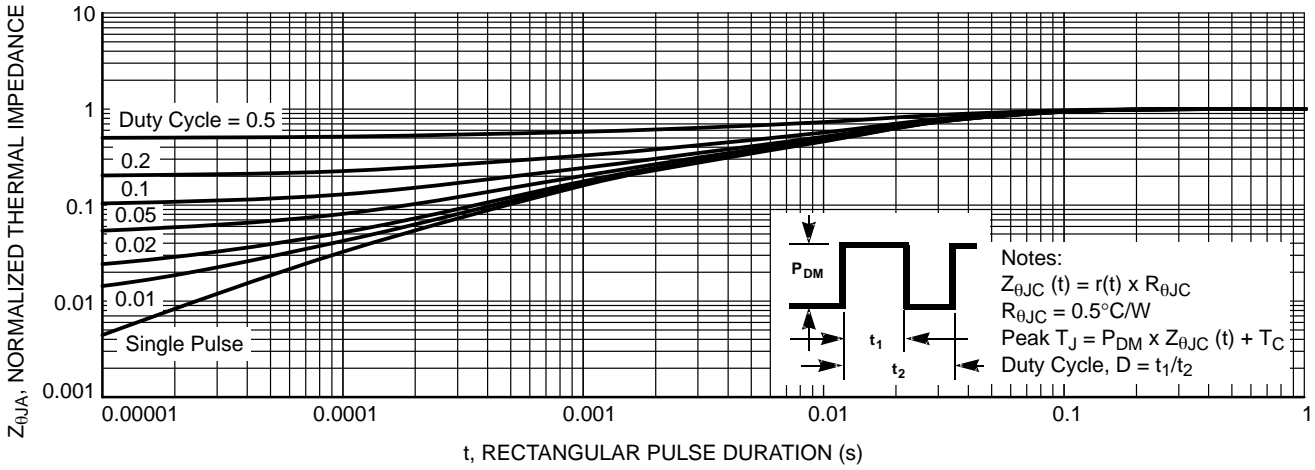


Figure 13. Transient Thermal Impedance

DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping†
NTBLS1D5N08MC	NTBLS 1D5N08MC	M0-299A (Pb-Free)	2000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

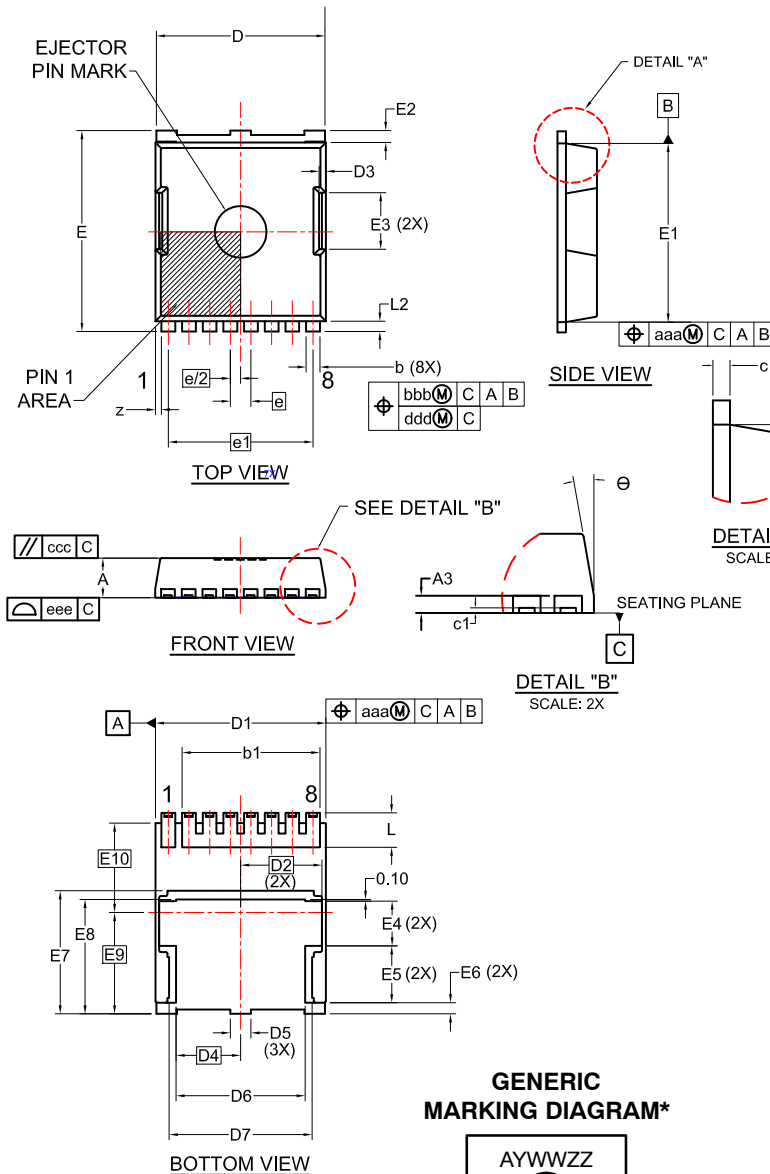
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



H-PSOF8L 11.68x9.80 CASE 100CU ISSUE A

DATE 06 JAN 2020



LAND PATTERN RECOMMENDATION
*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

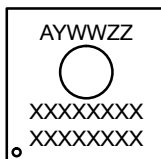
NOTES:

1. PACKAGE STANDARD REFERENCE: JEDEC MO-299, ISSUE A.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
3. CONTROLLING DIMENSION: MILLIMETERS.
4. COPLANARITY APPLIES TO THE EXPOSED WELL AS THE TERMINALS.
5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
6. SEATING PLANE IS DEFINED BY THE TERMINALS. "A1" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	2.20	2.30	2.40
A3	0.40	0.50	0.60
b	0.70	0.80	0.90
b1	8.00 REF		
c	0.40	0.50	0.60
c1	0.10	--	--
D	9.70	9.80	9.90
D1	9.80	9.90	10.00
D2	4.73 BSC		
D3	0.40 REF		
D4	3.75 BSC		
D5	--	1.20	--
D6	7.40	7.50	7.60
D7	(8.30)		
E	11.58	11.68	11.78
E1	10.28	10.38	10.48
E2	0.60	0.70	0.80
E3	3.30 REF		
E4	--	2.60	--

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
e	1.20 BSC		
e/2	0.60 BSC		
e1	8.40 BSC		
K	1.50	1.57	1.70
L	1.90	2.00	2.10
L2	0.50	0.60	0.70
z	0.35 REF		
θ	0°	--	12°
aaa	0.20		
bbb	0.25		
ccc	0.20		
ddd	0.20		
eee	0.10		
E5	--	3.30	--
E6	--	0.65	--
E7	7.15 REF		
E8	6.55	6.65	6.75
E9	5.89 BSC		
E10	5.19 BSC		

GENERIC MARKING DIAGRAM*



- A = Assembly Location
- Y = Year
- WW = Work Week
- ZZ = Assembly Lot Code
- XXXX = Specific Device Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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TECHNICAL SUPPORT

North American Technical Support:

Voice Mail: 1 800-282-9855 Toll Free USA/Canada

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